



Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Type: **PCB Mount Receptacle**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **8**

Number of Rows: **1**

Features

Product Type Features

PCB Connector Type	PCB Mount Receptacle
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Connector Product Type	Connector Assembly

Configuration Features

Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	8
Number of Rows	1

Body Features

Connector Profile	Standard
Primary Product Color	Black



Contact Features

Mating Pin Diameter	.63 mm[.024 in]
Mating Square Post Dimension	.63 mm[.024 in]
Contact Shape & Form	Square
PCB Contact Termination Area Plating Material Thickness	3 – 5 µm[118.11 – 196.85 µin]
Contact Layout	Inline
Contact Protection Type	Closed Entry Housing
Contact Base Material	Phosphor Bronze
PCB Contact Termination Area Plating Material	Tin
Contact Mating Area Plating Material	Gold (Au)
Contact Type	Socket
Contact Current Rating (Max)	3 A

Termination Features

Rectangular Termination Post & Tail Width	.69 mm[.027 in]
Rectangular Termination Post & Tail Thickness	.2 mm[.008 in]
Termination Post & Tail Length	3.1 mm[.122 in]
Termination Method to PCB	Through Hole - Solder

Mechanical Attachment

PCB Mount Retention Type	Retention Solder Tails
PCB Mount Retention	With

Housing Features

Mating Entry Location	Top
Housing Material	Polyester GF
Centerline (Pitch)	2.54 mm[.1 in]

Dimensions

PCB Thickness (Recommended)	1.6 mm[.063 in]
Connector Height	7 mm[.276 in]

Usage Conditions

Operating Temperature Range	-65 – 125 °C[-67 – 221 °F][-85 – 257 °F]
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Operation/Application

Solder Process Feature	Board Standoff
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Industry Standards



UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Quantity	88
Packaging Method	Carton

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) ‘Guidance on requirements for substances in articles’ posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



TE Part # 966710-8
MODU II PIN HEADER, SGL ROW,
SMD- 8 POS



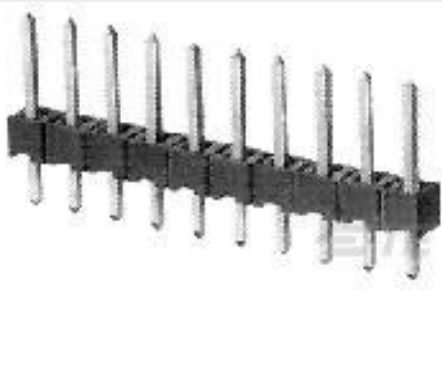
TE Part # 966306-8
MOD2 ST-LEI SMD 8P



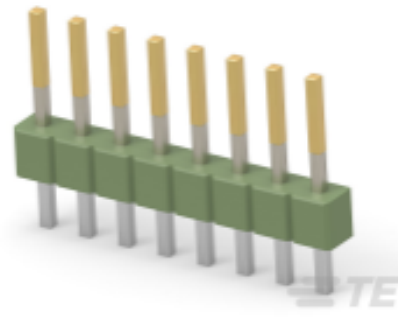
TE Part # 826646-8
8P AMPMODU II STIFT LEI



TE Part # 826647-8
8P AMPMODU II STIFT LEI



TE Part # 826630-8
8P AMPMODU II STIFT LEI



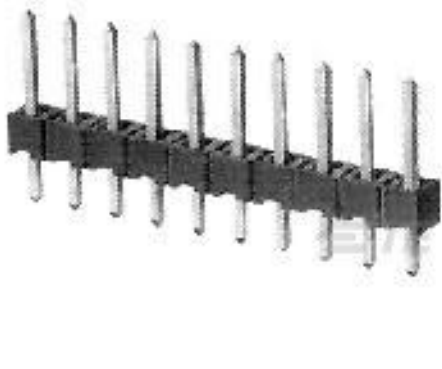
TE Part # 826629-8
AMPMODU II HEADER



TE Part # 826631-8
AMPMODU II PIN HEADER



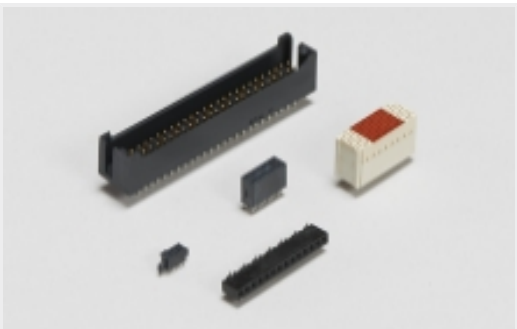
TE Part # 1241150-8
8P MOD II BREAK AWAY HDR, SMD, BLISTER



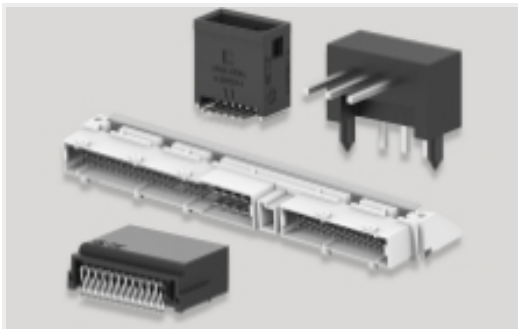
TE Part # 826648-8
08P AMPMODU II PIN HDR.

Also in the Series

AMPMODU HV-100/HV-190

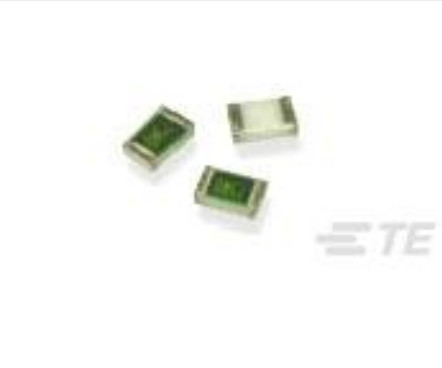


Board-to-Board Headers & Receptacles(321)

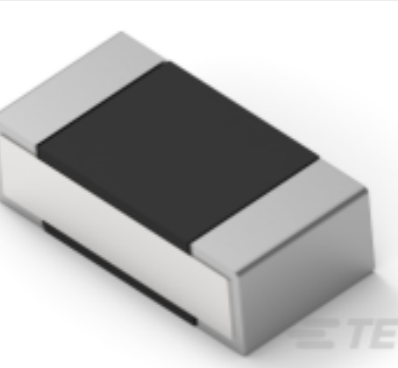


PCB Headers & Receptacles(321)

Customers Also Bought



TE Part #3-1625868-5
RP 2A 0.25W 12R1 0.1% 25PPM 1K RL



TE Part #7-2176311-0
RP 1E 0.1W 6K04 0.1% 25PPM 1K RL



TE Part #2013297-1
SEMI-HARD TRAY DDR3 204P 8H ST



TE Part #1-5499141-1
A/L UNIV HDR 60P RA LAT



TE Part #1415039-1
RTH34024



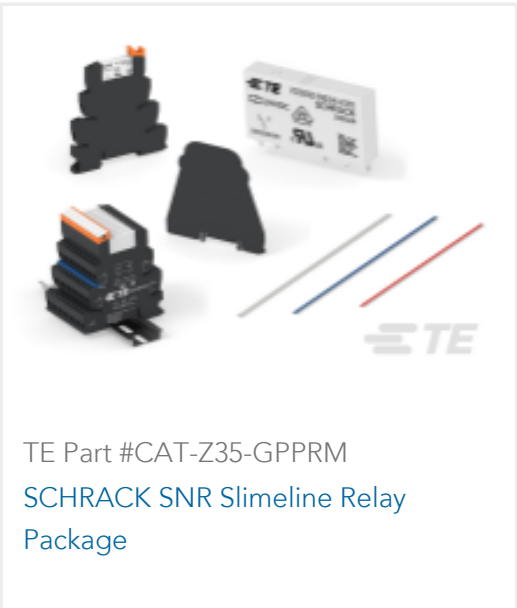
TE Part #2176070-4
3521 13R 1% 2W



TE Part #254702-E
SRCA 2,54 6 M 1 SMD 137 E1 168 * GURT *



TE Part #8-1419132-9
PT580615



Documents

Product Drawings

8P HV100 REC CON. TE, 7.0MM

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_215297-8_E.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_215297-8_E.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_215297-8_E.3d_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

1773393_ AMPMODU_EUROPEAN_STANDARD_PRODUCTS

English

Product Specifications

Product Specification

English